

Certificate TW02/00191

The management system of

KING YUAN ELECTRONICS CO., LTD.

No. 118, Chung-Hua Rd., and No. 8, Lane 228, Chung-Hua Rd., Chu-Nan, Miao-Li Hsien 350, Taiwan, R.O.C.

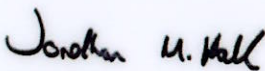
has been assessed and certified as meeting the requirements of
ISO 14001:2015

For the following activities

1. Manufacturing of semiconductor through grinding, dicing, probing, testing and backend processing.
2. Manufacturing of IC Package and Module Assembly.
3. Provision of Integrated Circuit Testing and Packaging Services

This certificate is valid from 30 December 2023 until 30 December 2026 and remains valid subject to satisfactory surveillance audits.
Issue 10. Certified since 30 December 2002

Certified activities performed by additional sites are listed on subsequent pages.



Authorised by
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Global Head - Certification Services

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KING YUAN ELECTRONICS CO., LTD.

ISO 14001:2015

Issue 10
Sites
<p>KING YUAN ELECTRONICS CO., LTD. No. 118, Chung-Hua Rd., and No. 8, Lane 228, Chung-Hua Rd., Chu-Nan, Miao-Li Hsien 350, Taiwan, R.O.C.</p> <p>1. Manufacturing of semiconductor through grinding, dicing, probing, testing and backend processing. 2. Manufacturing of IC Package and Module Assembly.</p>
<p>KING YUAN ELECTRONICS CO., LTD. CHU-NAN BRANCH CHUNG-HUA FACTORY No. 118, Chung-Hua Rd., and No. 8, Lane 228, Chung-Hua Rd., Chu-Nan, Miao-Li Hsien 350, Taiwan, R.O.C.</p> <p>1. Manufacturing of semiconductor through grinding, dicing, probing, testing and backend processing. 2. Manufacturing of IC Package and Module Assembly.</p>
<p>KING YUAN ELECTRONICS CO., LTD. ASSEMBLY OF SEMICONDUCTOR FACTORY No. 118, Chung-Hua Rd., Chu-Nan, Miao-Li Hsien 350, Taiwan, R.O.C.</p> <p>1. Manufacturing of semiconductor through grinding, dicing, probing, testing and backend processing. 2. Manufacturing of IC Package and Module Assembly.</p>
<p>KING YUAN ELECTRONICS CO., LTD. THIRD FACTORY 3-5 F, No. 81, Sec. 2, Gongdaowu Rd. Hsinchu City 300, Taiwan, R.O.C.</p> <p>1. Manufacturing of semiconductor through grinding, dicing, probing, testing and backend processing. 2. Manufacturing of IC Package and Module Assembly.</p>



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KING YUAN ELECTRONICS CO., LTD. SIXTH FACTORY
No. 81, Sec. 2, Gongdaowu Rd. Hsinchu City 300, Taiwan, R.O.C.

1. Manufacturing of semiconductor through grinding, dicing, probing, testing and backend processing.
2. Manufacturing of IC Package and Module Assembly.

KING YUAN ELECTRONICS CO., LTD. TONG-LUO BRANCH
No. 8, Tongke N. Rd., Tong-Luo, Miao-Li Hsien 366, Taiwan, R.O.C.

1. Manufacturing of semiconductor through grinding, dicing, probing, testing and backend processing.
2. Manufacturing of IC Package and Module Assembly.

